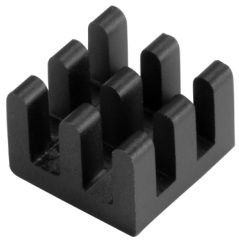
CUI DEVICES

MODEL: HSB02-101007 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- small footprint
- aluminum alloy
- black anodized finish



RoHS

MODEL

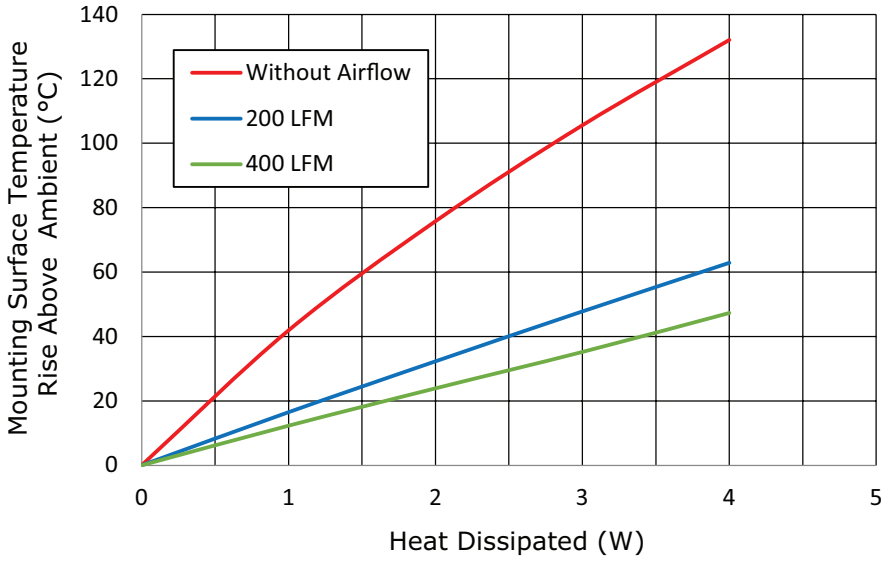
MODEL	thermal resistance[1]				power dissipation[1]
	@ 75°C ΔT, nat conv (°C/W)	**@ 1 W, nat conv** (°C/W)	**@ 1 W, 200 LFM** (°C/W)	**@ 1 W, 400 LFM** (°C/W)	**@ 75°C ΔT, nat conv** (W)
HSB02-101007	37.90	41.9	16.50	12.30	1.98

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	41.9	16.5	12.3
2	75.8	32.3	23.9
3	105.6	47.8	35.2
4	132.1	62.9	47.3

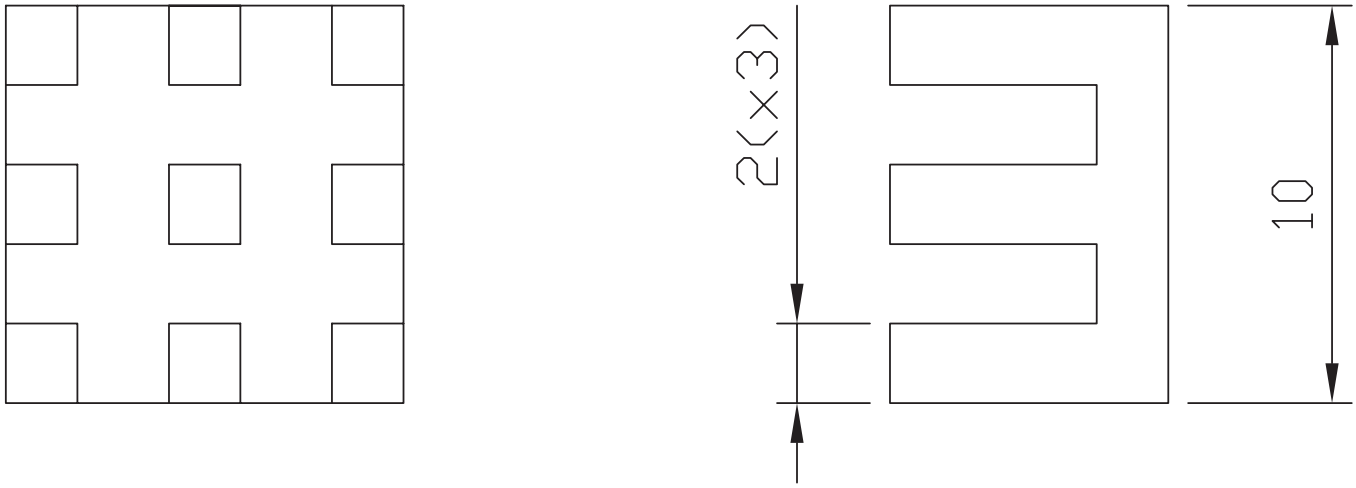
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature

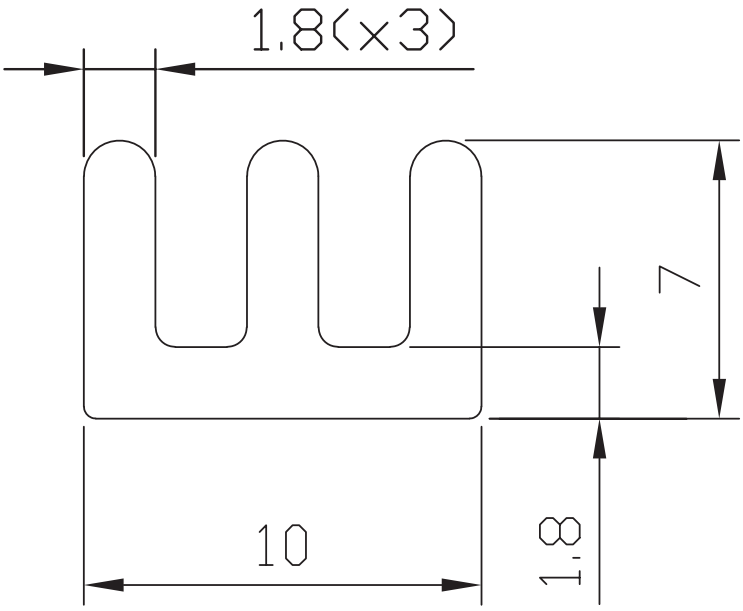


MECHANICAL DRAWING

units: mm
tolerance: ±0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	1.2 g





REVISION HISTORY

rev.	description	date
1.0	initial release	06/24/2021

The revision history provided is for informational purposes only and is believed to be accurate.